

Bill of Materials	
Project:	KIV_BatteryModuleConnectorBoard.Prj
Revision:	2.0
Project Lead:	Aashmika Mali
Generated On:	2019-12-01 10:27 PM
Production Quantity:	1
Currency	USD
Total Parts Count:	15

Project:	KIV_BatteryModuleConnectorBoard.PriPcb
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Revision:	2.0
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Project Lead:	Aashmika Mali
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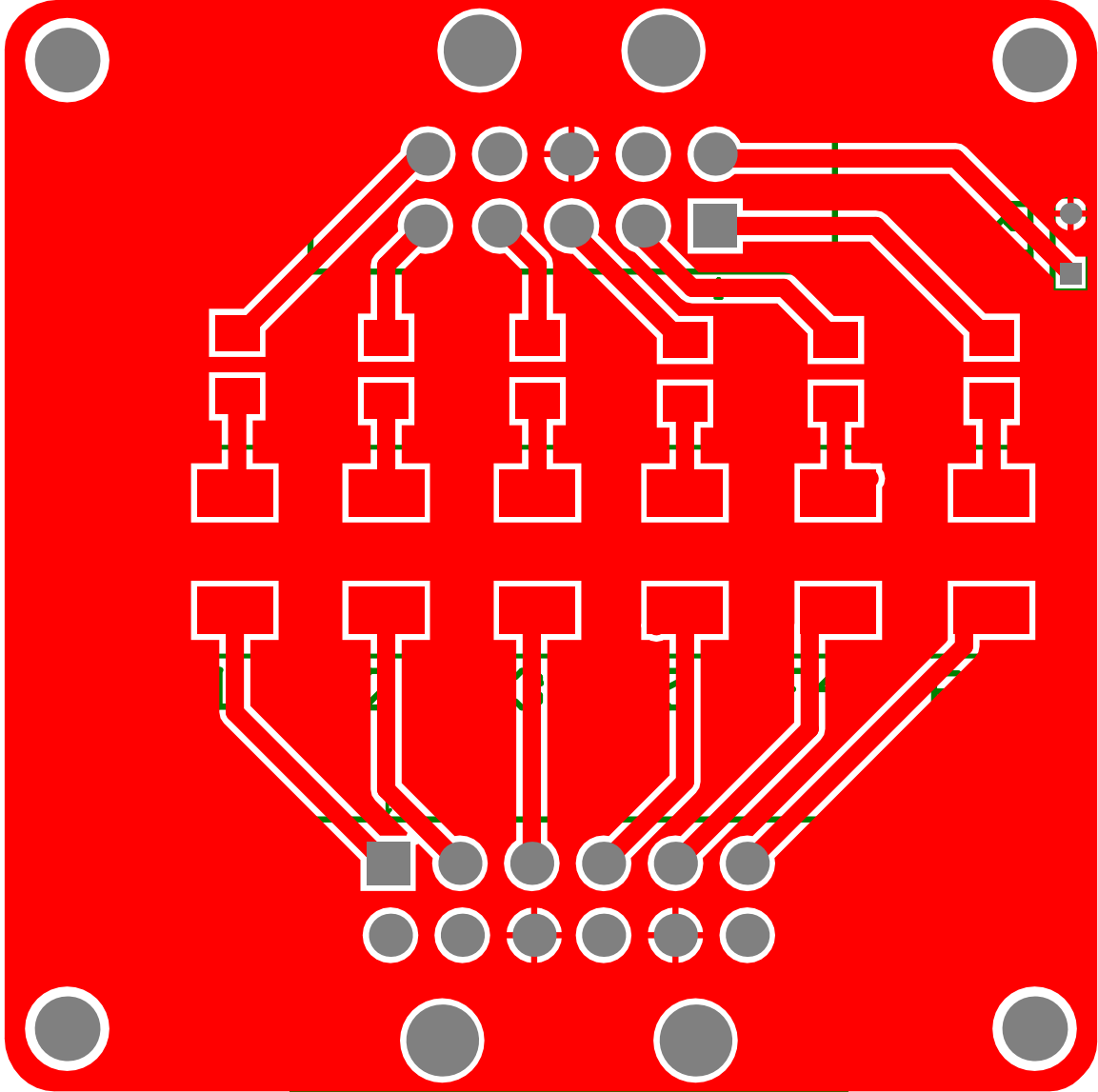
Generated On:	2019-12-01 10:27 PM
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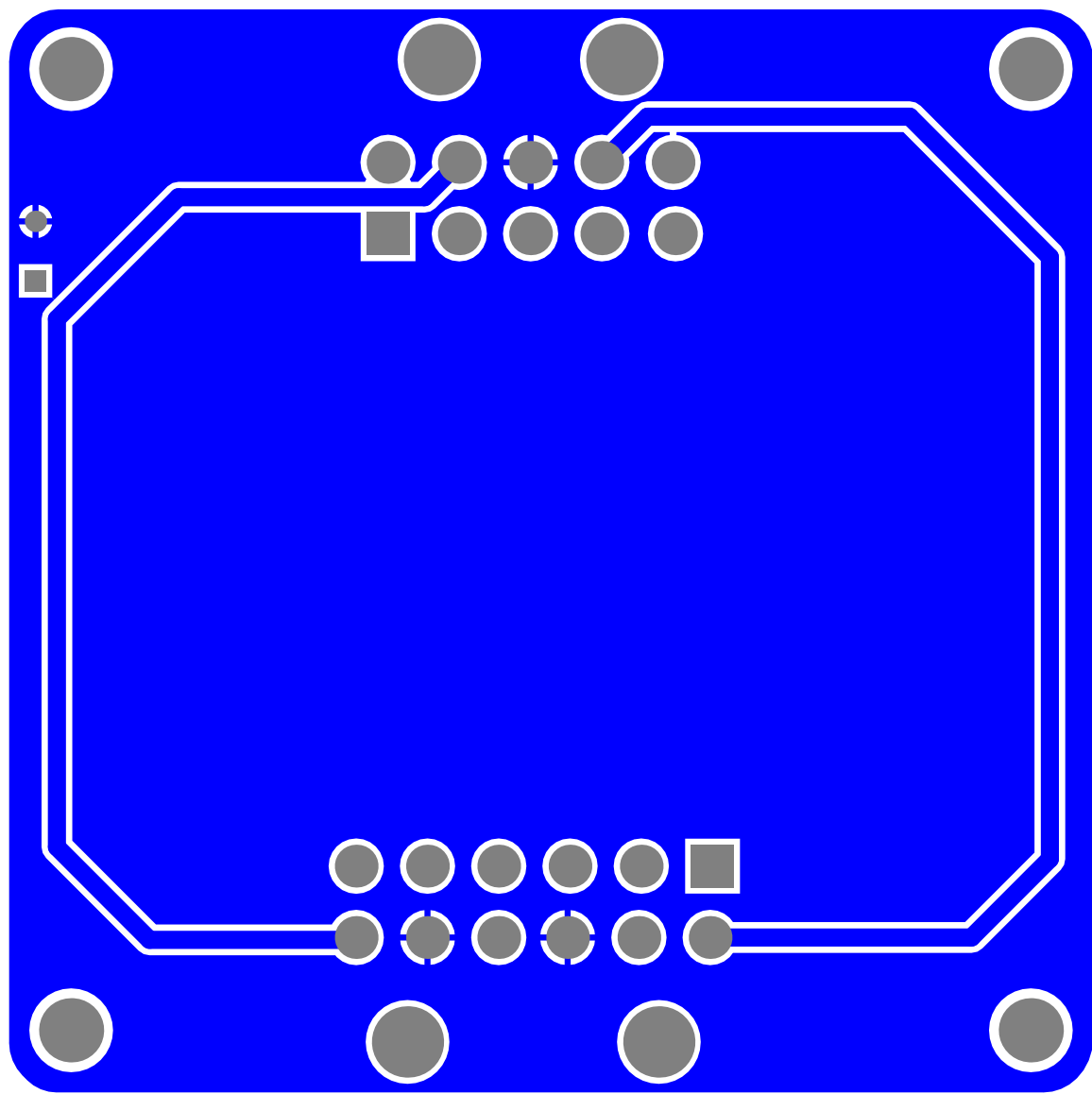
Production Quantity:	1
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Currency	USD
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Total Parts Count:	15
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[illegible]





MSXIV BATTERY
MODULE
CONNECTOR BOARD

To Battery
Module

F1

F2

F3

F5

F4

F6

R1

R2

R3

R5

R4

R6

To AFE

10

1

12

P2

P1

RT1

Design Rules Verification Report

Filename : C:\Users\Midnight Sun\Documents\Midnight Sun\hardware\MSXIV_BatteryM

Warnings 0
Rule Violations 17

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.254mm) (All),(All)	1
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint (All)	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.254mm) (Max=0.762mm) (Preferred=0.508mm) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	8
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	0
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	6
Silk to Silk (Clearance=0.254mm) (All),(All)	2
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Preferred=12.7mm) (All)	0
Total	17

Clearance Constraint (Gap=0.254mm) (All),(All)	
Clearance Constraint: (0.184mm < 0.254mm) Between Pad P1-6(30.06mm,39.48mm) on Multi-Layer And Track	

Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	
Hole Size Constraint: (3mm > 2.54mm) Pad Free-(3mm,3mm) on Multi-Layer Actual Hole Size = 3mm	
Hole Size Constraint: (3mm > 2.54mm) Pad Free-(3mm,43.4mm) on Multi-Layer Actual Hole Size = 3mm	
Hole Size Constraint: (3mm > 2.54mm) Pad Free-(43.4mm,3mm) on Multi-Layer Actual Hole Size = 3mm	
Hole Size Constraint: (3mm > 2.54mm) Pad Free-(43.4mm,43.4mm) on Multi-Layer Actual Hole Size = 3mm	
Hole Size Constraint: (3mm > 2.54mm) Pad P1-(20.22mm,43.8mm) on Multi-Layer Actual Hole Size = 3mm	
Hole Size Constraint: (3mm > 2.54mm) Pad P1-(27.9mm,43.8mm) on Multi-Layer Actual Hole Size = 3mm	
Hole Size Constraint: (3mm > 2.54mm) Pad P2-(18.66mm,2.51mm) on Multi-Layer Actual Hole Size = 3mm	
Hole Size Constraint: (3mm > 2.54mm) Pad P2-(29.24mm,2.51mm) on Multi-Layer Actual Hole Size = 3mm	

Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	
Silk To Solder Mask Clearance Constraint: (0.173mm < 0.254mm) Between Pad RT1-1(44.9mm,34.5mm) on Multi-Layer And Track	
Silk To Solder Mask Clearance Constraint: (0.173mm < 0.254mm) Between Pad RT1-1(44.9mm,34.5mm) on Multi-Layer And Track	
Silk To Solder Mask Clearance Constraint: (0.173mm < 0.254mm) Between Pad RT1-1(44.9mm,34.5mm) on Multi-Layer And Track	
Silk To Solder Mask Clearance Constraint: (0.252mm < 0.254mm) Between Pad RT1-2(44.9mm,37mm) on Multi-Layer And Track	
Silk To Solder Mask Clearance Constraint: (0.238mm < 0.254mm) Between Pad RT1-2(44.9mm,37mm) on Multi-Layer And Track	
Silk To Solder Mask Clearance Constraint: (0.252mm < 0.254mm) Between Pad RT1-2(44.9mm,37mm) on Multi-Layer And Track	

Silk to Silk (Clearance=0.254mm) (All),(All)	
Silk To Silk Clearance Constraint: (0.068mm < 0.254mm) Between Text "1" (16.5mm,12.8mm) on Top Overlay And Track	
Silk To Silk Clearance Constraint: (0.098mm < 0.254mm) Between Text "1" (30.06mm,33.48mm) on Top Overlay And Track	